

PROCESS FOR PREPARING A THIN LAYER**ABSTRACT**

The present invention relates to a process for preparing a thin layer (1) comprising a weakening step (S2) aiming to form a weakened zone (3) in a central portion (2c) of a donor substrate (2), the weakened zone (3) not extending into a peripheral portion (2p) of the donor substrate (2); a step of joining (S3) the main face (2a) of the donor substrate (2) to a receiver substrate (5) in order to form an assembly to be split; and a step of separating (S4) the assembly to be split, the separating step comprising a heat treatment resulting in the freeing of the thin layer (1) from the donor substrate (2) at the central portion (2c) thereof only. The process also comprises, after the separating step, a detaching step (S6) comprising the treating of the assembly to be split in order to detach the peripheral portion of the donor substrate (2) from the receiver substrate (5).

Figure 1